

PCN Number:	20210713001.1	PCN Date:	July 20, 2021
Title:	Qualification of additional Fab site (RFAB), Datasheet update and additional Assembly site/BOM options for select LBC7 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Oct. 20, 2021	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process
<input checked="" type="checkbox"/>	Assembly Materials	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Bump Process	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>	Wafer Fab Process	<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of an additional fab (RFAB) and assembly (CDAT) site/BOM options for selected devices as listed below in the product affected section.

Current Site			Additional Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
FFAB	LBC7	200mm	RFAB	LBC7	300mm

Construction differences are noted below:

Group 1 Adding RFAB + Clark adding CDAT A/T:

No Material differences between sites

Group 2 Adding RFAB + MLA adding CDAT A/T Site, BOM Change:

	MLA	CDAT
Mount Compound	4207768	4207123
Mold Compound	4208625	4222198

In addition, the datasheet number will be changing for the devices listed in group 3:

Device Family	Change From:	Change To:
TPS22930A	SLVSBL3C	SLVSBL3D



TPS22930

SLVSBL3D – NOVEMBER 2012 – REVISED JULY 2021

Changes from Revision C (January 2021) to Revision D (July 2021)

Page

- Updated $I_{RCP(Leak)}$ spec to 2.6 μA5

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/TPS22930>

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .
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Changes to product identification resulting from this PCN:**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising
RFAB	RFB	USA	Richardson

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI Malaysia	MLA	MYS	Kuala Lumpur
TI Clark	QAB	PHL	Angeles City, Pampanga
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)

Product Affected:**Group 1 Device List: Adding RFAB + TI-Clark adding CDAT A/T Site**

TPS62175DQCR	TPS62175DQCT	TPS62177DQCR	TPS62177DQCT
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Group 2 Device List: Adding RFAB + MLA adding CDAT A/T Site and BOM Change

TCA6416ARTWR	TCA1116RTWR	TCA9539RTWR	TCA9555RTWR
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Group 3 Device List: Adding RFAB Wafer Fab site + Datasheet change

TPS22930AYZVR	TPS22930AYZVT
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Group 4 Device List: Adding RFAB Wafer Fab site

TLV7031DCKT	TPS7A8701RTJT	TPS7A8801RTJR	TPS7A8801RTJT
TPS7A8701RTJR			

Qualification Report

Approve Date 6-October-2010

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS51217DSC
ED	Electrical Characterization	Per Datasheet Parameters	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
AC	Autoclave, 121C	96 Hours	3/231/0
HBM	ESD - HBM	2000 V	3/9/0
CDM	ESD - CDM	500 V	3/9/0
HTOL	Life Test, 135C	635 Hours	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0
LU	Latch-up	(per JESD78)	3/18/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/18/0

- Qual Device TPS51217DSC is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

Qualification Report

Approve Date 02-June-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TCA6416ARTWR	Qual Device: TCA9555RTWR	Qual Device: TCA1116RTWR	Qual Device: TCA9539RTWR	QBS Package Reference: THS4552IRTW	QBS Package Reference: TMP116AIDRV
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	-	-	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	-
SD	Solderability	PB Free	-	-	-	-	2/44/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0
WBP	Bond Pull	Wires	1/30/0	1/30/0	1/30/0	1/30/0	-	-
WBS	Ball Bond Shear	Wires	1/30/0	1/30/0	1/30/0	1/30/0	-	-

- Qual Device TCA6416ARTWR is qualified at LEVEL2-260C

- Qual Device TCA9555RTWR is qualified at LEVEL2-260C

- Qual Device TCA1116RTWR is qualified at LEVEL2-260C

- Qual Device TCA9539RTWR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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